

Layer Stack Up Detail for: PMP9334 RevB.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	1.4mil	FR-4
MidLayer1	(.G1)	0.7mil	FR-4
GND	(.G2)	0.7mil	FR-4
Bottom Layer	(.GBL)	1.4mil	FR-4
Bottom Solder Mask	(.GBS)		Solder Resist

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
3999MIL X 1100MIL

Number of Layers : 4
 MIN. TRACK WIDTH: 10 MIL
 MIN. CLEARANCE: 7.8MIL
 MIN. VIA PAD SIZE: 10 MIL

MINIMUM ANNULAR RING 0.125mm (5MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
 FR-4 FR-4 High Tg OTHER _____
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

COPPER THICKNESS (FINISHED):
 OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)
 INNER SIGNAL: 0.7MIL (0.5oz) 2.8MIL (2oz) N/A

DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

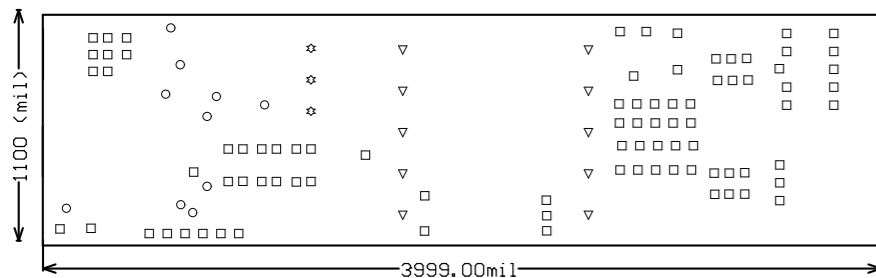
BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR:
 GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENIG)
 IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S ID/LOGO: RAIL METAL SILK



Symbol	Hit Count	Tool Size	Plated	Hole Type
○	10	15mil (0.381mm)	PTH	Round
□	85	28mil (0.711mm)	PTH	Round
☆	3	45mil (1.143mm)	PTH	Round
▽	10	47.244mil (1.2mm)	PTH	Round
	108 Total			

Drill Table



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9334	REV: B	SUN REV: Not In VersionControl	Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.
LAYER NAME = 00000 Fabrication Drawing				
PLOT NAME = Fabrication Drawing	GENERATED : 2/2/2015 2:47:48 PM	TEXAS INSTRUMENTS		

TEXAS INSTRUMENTS

PROJECT TITLE:
LM5022 HV Isolated Flyback

DESIGNED FOR:
Public Release

FILE NAME:
PMP9334 RevB.PcbDoc

ENGINEER:
Xinyu Dai

LAYOUT BY:
Xinyu Dai

SCALE: 1.10

ALTIM DESIGNER VERSION:
10.0.0.27009

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